



# RABS22 THRU RABS210

## GLASS PASSIVATED FAST RECOVERY BRIDGE RECTIFIERS

Voltage Range - 200 to 1000 Volts    Current - 2.0 Ampere

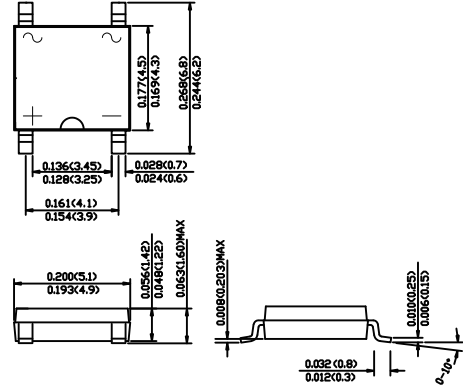
### FEATURES

Ideal for printed circuit board  
 Reliable low cost construction utilizing molded plastic technique  
 High temperature soldering guaranteed:  
 260°C/10 seconds at 5 lbs., (2.3kg) tension  
 Small size, simple installation  
 Leads solderable per MIL-STD-202, Method 208  
 High surge current capability  
 Glass passivated chip junction  
 Green compound(halogen&Sb<sub>2</sub>O<sub>3</sub> free)

### MECHANICAL DATA

**Case:** Molded plastic body  
**Terminals:** Plated leads solderable per MIL-STD-750, Method 2026  
**Polarity:** Polarity symbols marked on case  
**Mounting Position:** Any

### ABS



Dimensions in inches and (millimeters)

### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.  
 Single phase half-wave 60Hz, resistive or inductive load, for capacitive load derate current by 20%.

	SYMBOLS	RABS22	RABS24	RABS26	RABS28	RABS210	UNITS	
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	200	400	600	800	1000	V	
Maximum RMS voltage	V <sub>RMS</sub>	140	280	420	560	700	V	
Maximum DC blocking voltage	V <sub>DC</sub>	200	400	600	800	1000	V	
Maximum average forward rectified current On glass-epoxy P.C.B.(Note1) On aluminum substrate(Note2)	I <sub>F(AV)</sub>						1.6 2.0	A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>						50	A
Maximum instantaneous forward voltage drop per leg at 1.0A	V <sub>F</sub>						1.3	V
Maximum DC reverse current at rated DC blocking voltage	I <sub>R</sub>						5.0 500	uA uA
Typical thermal resistance(NOTE 3)	R <sub>θJL</sub>						20	°C/W
	R <sub>θJA</sub>						55	
Maximum reverse recovery time (NOTE 4)	t <sub>rr</sub>	150		250	500		ns	
Operating temperature range	T <sub>J</sub>						-55 to +150	°C
storage temperature range	T <sub>STG</sub>						-55 to +150	°C

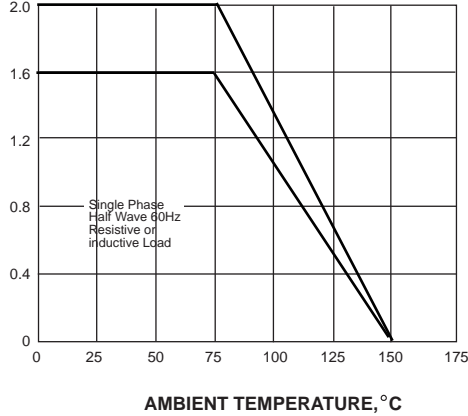
NOTES:1.On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads.  
 2.On aluminum substrate P.C.B. with an area of 0.8"x0.8"(20x20mm) mounted on 0.05X0.05"(1.3X1.3mm) solder pad.  
 3.Thermal resistance from junction to ambient and junction to lead mounted on P.C.B. with 0.2X0.2"(5X5mm) copper pads.  
 4.Reverse recovery condition I<sub>F</sub>=0.5A,I<sub>R</sub>=1.0A,I<sub>rr</sub>=0.25A.



## RATINGS AND CHARACTERISTIC CURVES RABS22 THRU RABS210

AVERAGE FORWARD RECTIFIED CURRENT, AMPERES

FIG. 1- FORWARD CURRENT DERATING CURVE



PEAK FORWARD SURGE CURRENT, AMPERES

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

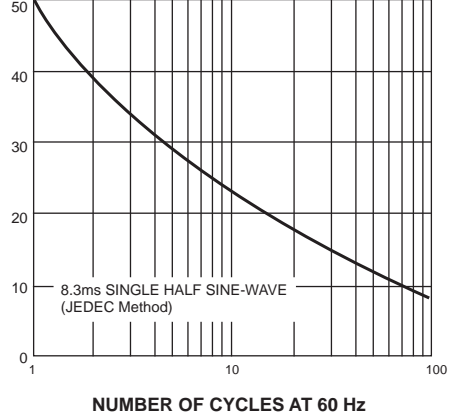


FIG.3 TYPICAL FORWARD CHARACTERISTICS

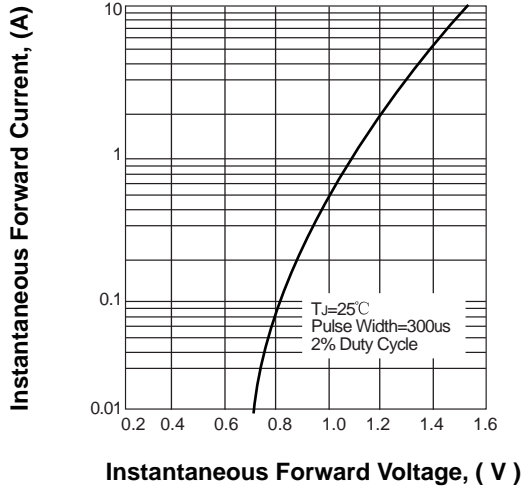


FIG.4 TYPICAL REVERSE CHARACTERISTICS

